



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPP410N30N	Issued	04. May 2021
MA#	MA001158662		
Package	PG-TO220-3-1	Weight*	2047.03 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	0.86	0.86	8579	8579
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		399	
	non noble metal	copper	7440-50-8	815.335	39.83	39.88	398301	398820
wire	non noble metal	aluminium	7429-90-5	13.797	0.67	0.67	6740	6740
encapsulation	inorganic material	zinc oxide	1314-13-2	5.770	0.28		2819	
	miscellaneous	miscellaneous	-	23.081	1.13		11275	
	plastics	epoxy resin	-	86.554	4.23		42283	
	inorganic material	silicon dioxide	60676-86-0	461.624	22.55	28.19	225509	281886
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10485	10485
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	119	120
solder	non noble metal	tin	7440-31-5	0.206	0.01		101	
	noble metal	silver	7440-22-4	0.258	0.01		126	
	non noble metal	lead	7439-92-1	9.839	0.48	0.50	4807	5034
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		86	
	non noble metal	iron	7439-89-6	0.590	0.03		288	
	non noble metal	copper	7440-50-8	589.466	28.80	28.84	287962	288336
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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